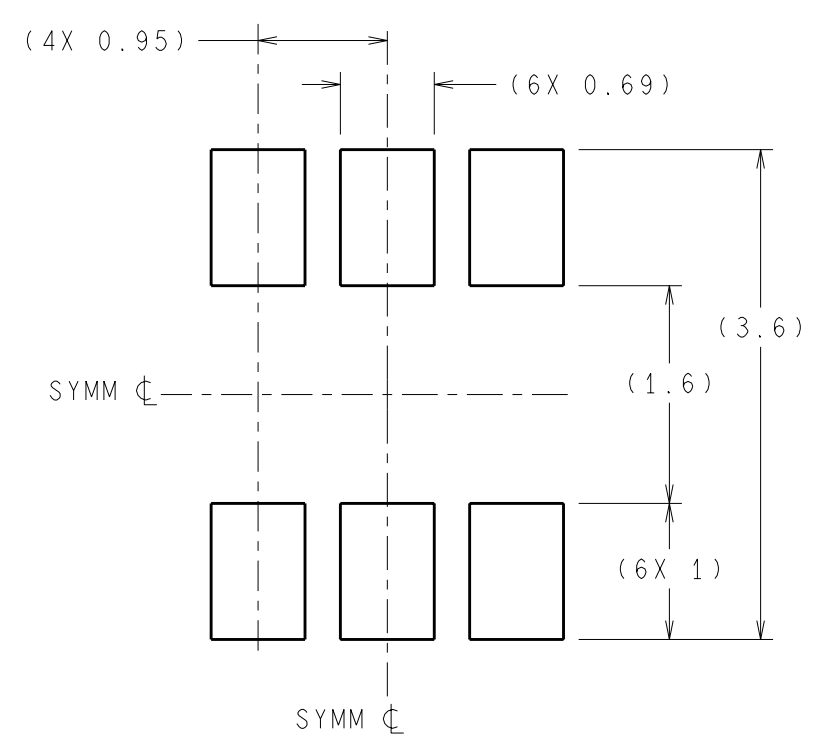
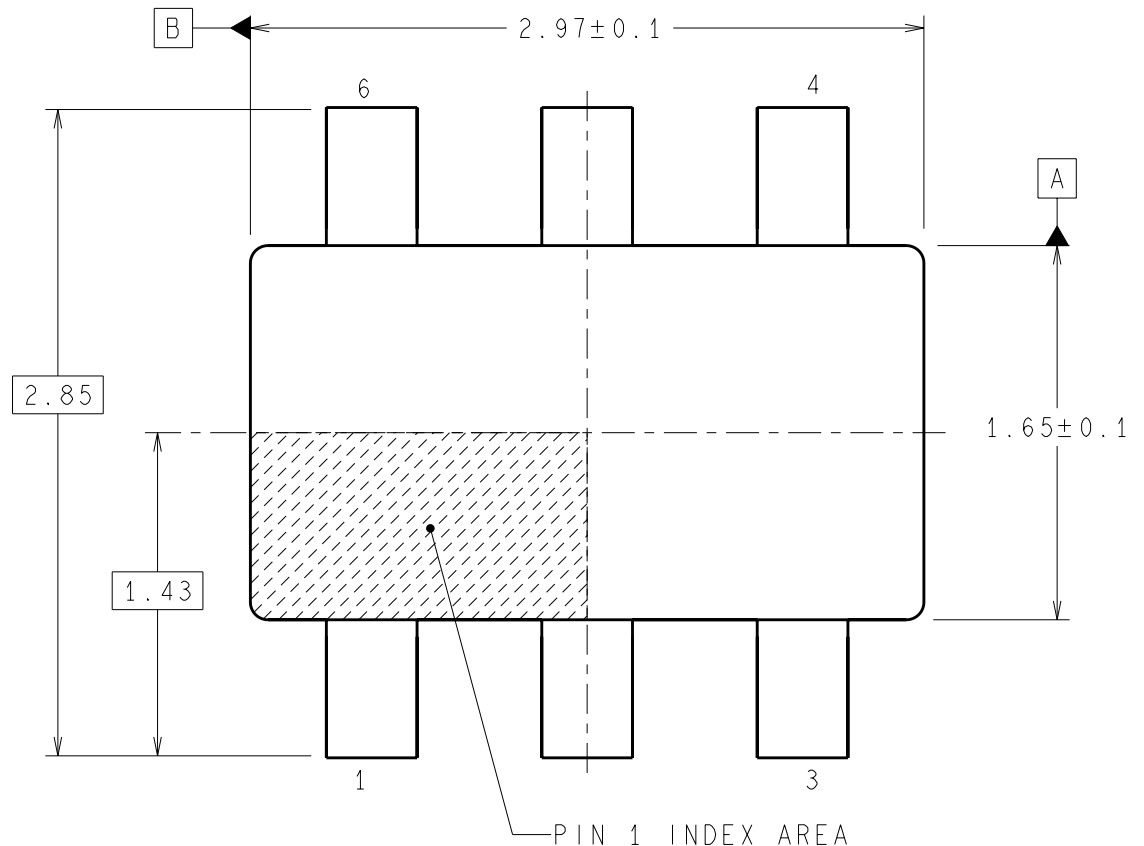
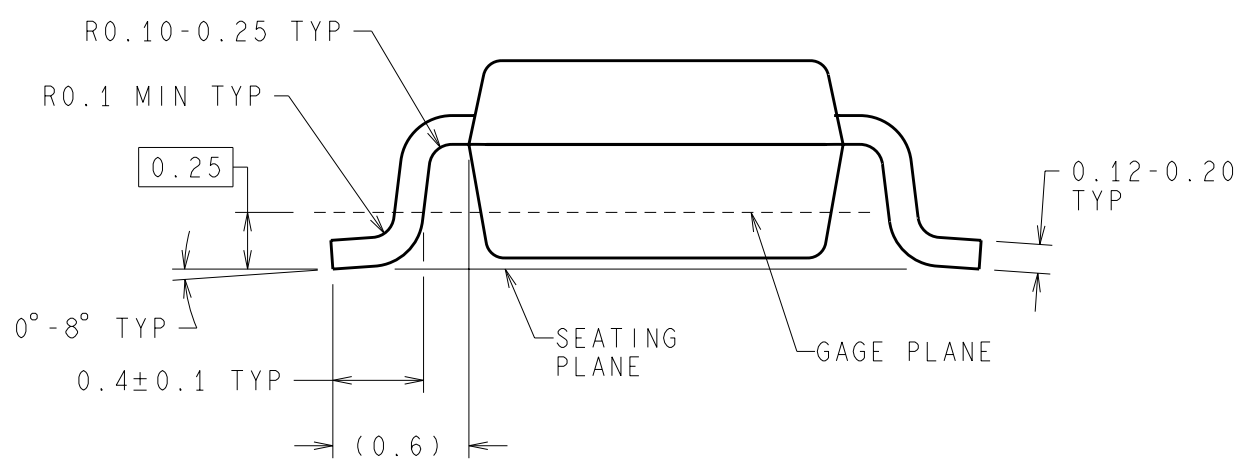
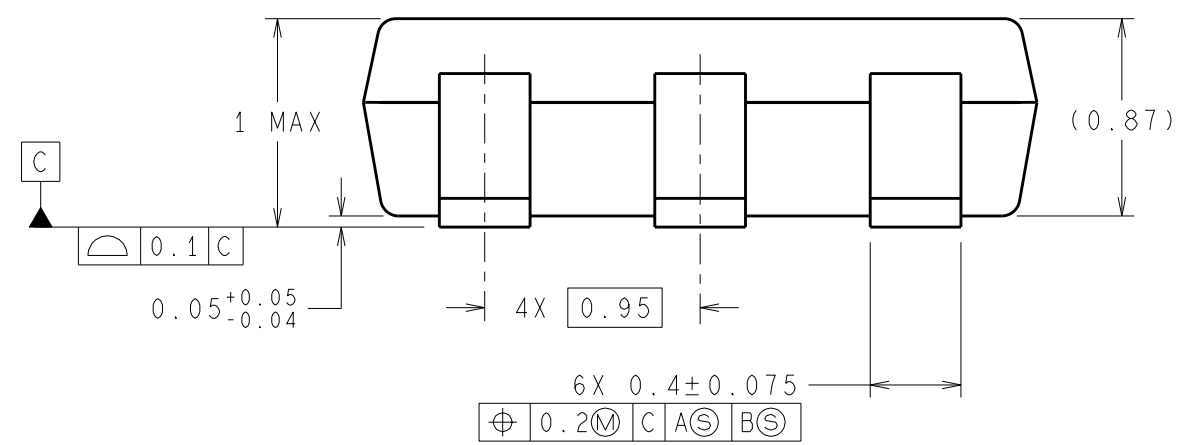


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	911	04/02/2003	MS/RW
B	1. BODY LENGTH FROM 2.9±0.1 TO 2.97±0.1 2. BODY WIDTH FROM 1.6±0.1 TO 1.65±0.1 3. LEAD WIDTH FROM 0.375±0.075 TO 0.400±0.075 4. LEAD SPREAD FROM 2.8 TO 2.85 5. CHANGE TITLE FROM 2.9x1.6x0.87mm BODY TO 2.97x1.65x0.87mm BODY	1611	10/04/2004	AS/TL/JLC
C	CORRECT DIM 2.97 TOL FROM ±0.01 TO ±0.1	1662	11/17/2004	TL/AS
D	DIMENSION 1 MAX WAS 0.9 MAX	1871	07/19/2005	AS/MS/AS
E	ADD PIN 1 INDEX AREA	2642	11/25/2008	TKY/TL/TKY



RECOMMENDED LAND PATTERN



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- REFERENCE JEDEC REGISTRATION MO-193, VARIATION AA.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN	MARTA SUCHY	04/02/2003			
DFTG. CHK.	THANH LEQUANG	11/25/2008			
ENGR. CHK.	TK YII	11/25/2008	<b>MOLDED TSOT,</b> <b>2.97x1.65x0.87mm,</b> <b>6 LD, 0.95mm PITCH</b>		
PROJECTION  MM					
SCALE	SIZE	DRAWING NUMBER	REV		
NTS	B	(SC)MKT-MK06A	E		
FORMERLY:			SHEET 1 of 1		